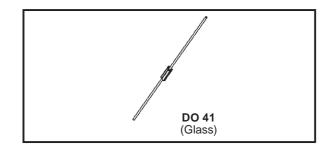


SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

General purpose metal to silicon diode featuring very low turn-on voltage and fast switching.

This device has integrated protection against excessive voltage such as electrostatic discharges.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
V_{RRM}	Repetitive Peak Reverse Voltage	80	V	
I _F	Forward Continuous Current* $T_a = 70 ^{\circ}\text{C}$		500	mA
I _{FRM}	Repetitive Peak Forward Current*	3	А	
I _{FSM}	Surge non Repetitive Forward Current*	10	А	
$T_{stg} \ T_{j}$	Storage and Junction Temperature Range	- 65 to 150 - 65 to 125	°C °C	
TL	Maximum Lead Temperature for Soldering duri	230	°C	

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
$R_{th(j-a)}$	Junction-ambient*	110	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Тур.	Max.	Unit
I _R * *	$T_j = 25^{\circ}C$ $V_R = 80V$			200	μΑ
V _F * *	$T_j = 25^{\circ}C$ $I_F = 10mA$			0.32	V
	$T_j = 25^{\circ}C$ $I_F = 100 \text{mA}$			0.42	
	$T_j = 25^{\circ}C$ $I_F = 1A$			1	

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
С	T _j = 25°C	f = 1MHz	$V_R = 0V$		120		pF
			V _R = 5V		35		

 $^{^*}$ On infinite heatsink with 4mm lead length ** Pulse test: $~t_p \! \leq \! 300 \mu s~\delta \! < \! 2\%$

August 1999 Ed: 1A

Figure 1. Forward current versus forward voltage at low level (typical values).

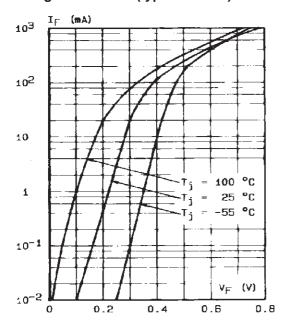


Figure 2. Forward current versus forward voltage at high level (typical values).

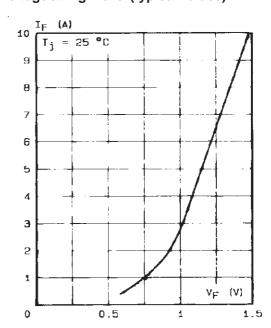


Figure 3. Reverse current versus junction temperature.

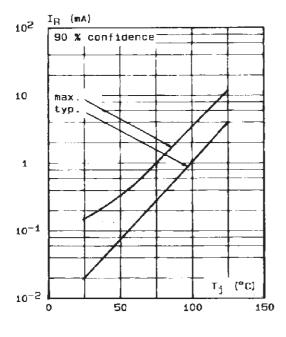


Figure 4. Reverse current versus $\ensuremath{V_{\text{RRM}}}$ in per cent.

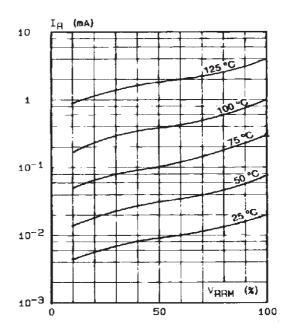


Figure 5. Capacitance C versus reverse applied voltage $V_{\mbox{\scriptsize R}}$ (typical values).

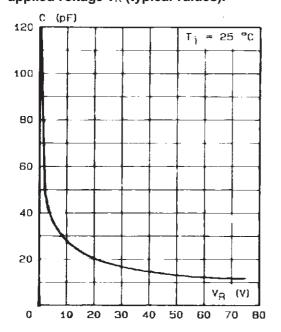


Figure 6. Surge non repetitive forward current for a rectangular pulse with $t \le 10 \text{ ms}$.

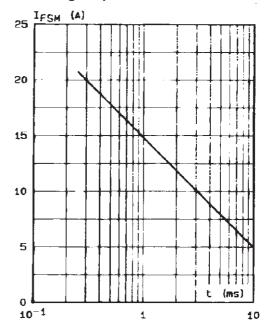
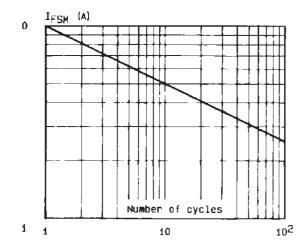
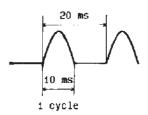


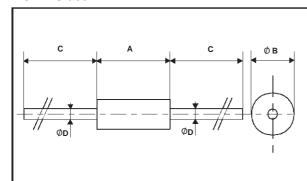
Figure 7. Surge non repetitive forward current versus number of cycles.





PACKAGE MECHANICAL DATA

DO 41 Glass



	DIMENSIONS				
REF.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
А	4.07	5.20	0.160	0.205	
В	2.04	2.71	0.080	0.107	
С	28		1.102		
D	0.712	0.863	0.028	0.034	

Cooling method: by convection and conduction Marking: clear, ring at cathode end. Weight: 0.34g

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